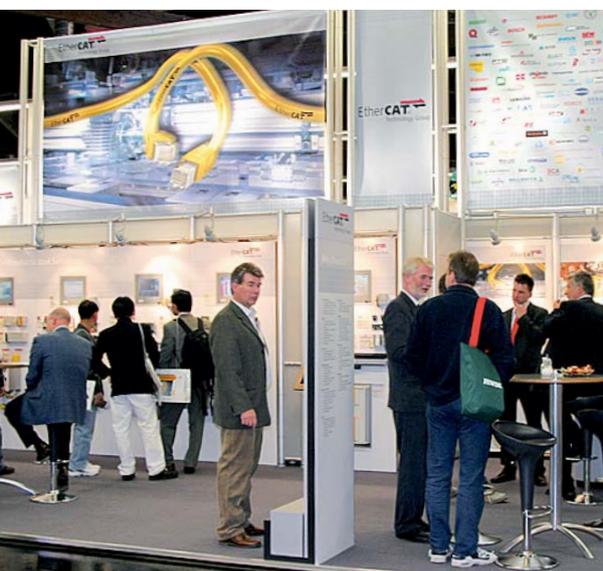# EtherCAT®
Technology Group

Further Information:
www.ethercat.org

**ETG trade fair booth through the ages:
2003 (above) and 2013 (below).**

Strong ETG presence at SPS IPC Drives for the 10ᵗʰ time

SPS IPC Drives in Nuremberg, Germany, is one of the most important trade fairs in the automation industry and is especially important for the EtherCAT Technology Group (ETG) this year.

Apart from the regular trade fair presence at the ETG organization booth, where visitors can marvel at the enormous variety of EtherCAT devices, the world's largest fieldbus user organization is also celebrating its very own milestone. After EtherCAT technology itself was presented for the first time at Hannover Fair in 2003, the EtherCAT Technology Group was founded the following November and has promoted the advancement of EtherCAT technology from the outset in its role as a user and manufacturer association: Everyone should be able to use and implement EtherCAT.

The ETG started off with 33 member companies at SPS IPC Drives 2003; in time for this year's fair, the organization has announced that there are now in excess of 2,500 members. There is no end in sight in terms of the ETG's growth, as Executive Director of the ETG, Martin Rostan, can confirm: "The staff and members of the EtherCAT Technology Group are looking forward to guiding the technology successfully through the next 10 years as well."

2013 EtherCAT seminars in Taiwan and South Korea

The EtherCAT Technology Group (ETG) conducted its series of Industrial Ethernet seminars in Taiwan and South Korea in September 2013. "We received very positive feedback from the 300 plus participants in Taipei, Tainan and Taichung, who all showed great general interest in EtherCAT as well as in the individual seminar topics," explains Beryl Fan, Manager of the ETG office in China. In South Korea, the EtherCAT Roadshow stopped off for the first time in Seoul and Daejeon and was very well attended with some 120 participants in total.

The seminars, which were free of charge for all participants, offered valuable and timely information on the use of EtherCAT as an Ethernet-based real-time communication system. The attendees learned details about EtherCAT technology and were given an insight into the variety of applications of EtherCAT as well as the numerous advantages and challenges arising from the use of Industrial Ethernet.

As usual, the EtherCAT seminars in Taiwan and South Korea were also supported by various ETG member companies who sponsored the event and introduced their EtherCAT implementations in real world-oriented project presentations.

**Impressions of the Industrial
Ethernet seminars hosted by
the ETG in Taiwan (left) and
South Korea (right)**

Numerous master and slave devices from different manufacturers were tested for interoperability at the North American EtherCAT Plug Fest 2013.

Some 45 participants gathered at this year's EtherCAT Technology Update in Yokohama to get information on EtherCAT and the ETG.

North American EtherCAT Plug Fest 2013

The annual North American EtherCAT Plug Fest of the EtherCAT Technology Group (ETG) took place in the US in September 2013 – this time at the company headquarters of Advanced Motion Controls in Camarillo, California. Over the two day event, 33 participants from 16 different ETG member companies attended in order to test six master and 18 slave devices with respect to interoperability. As with the recent EtherCAT Plug Fest in Japan, the semiconductor-specific devices the participants brought along attracted particular attention at the North American EtherCAT Plug Fest. According to Florian Hammel, who was in attendance as one of the ETG's EtherCAT experts providing support to participants at the event: "Although we only recently released the newly developed device profiles for the semiconductor industry, corresponding devices are already represented at our EtherCAT Plug Fests taking place around the globe. In North America especially, we are experiencing particularly strong interest in this area."

Aside from North America, the EtherCAT Plug Fests also take place several times each year in Europe and Asia. The events at which the ETG's EtherCAT Conformance Test Tool is used offer manufacturers of EtherCAT devices of all types the possibility to test the interoperability of their products with third-party devices at an early stage of development. As a result, any potentially defective device properties can be identified early on and resolved so that the products are readied for their launch on the market as efficiently as possible.

Furthermore, the participants benefit from the personal atmosphere that prevails at the EtherCAT Plug Fests: Open questions can be clarified directly through exchanges of expertise with the other participants and in discussions with the EtherCAT experts on-site.

EtherCAT Technology Update and Japanese EtherCAT Plug Fest 2013 in Yokohama

Success of EtherCAT in Japan continues unabated

This year's visit by the EtherCAT Technology Group (ETG) to Yokohama in Japan was very well received – just like last year. The event kicked off with the annual EtherCAT Technology Update, where the visitors – mainly developers and product managers of EtherCAT devices – were informed about developments in the individual ETG working groups and learned about the latest happenings in the area of EtherCAT technology. "Of particular interest this year were the results of the SEMI TWG, the EtherCAT Technology Working Group, which recently attracted attention for its specification of new device profiles for the semiconductor industry," reports Dr. Guido Beckmann, Chairman of the ETG Technical Committee and Event Director. In total, 45 participants attended and received information on the topic of "EtherCAT in Mobile Applications" as well as on the ETG's Safety-over-EtherCAT (FSoE) Conformance Test Tool, which was recently certified by the German certification organization, TÜV.

Following the Technology Update, the ETG issued an invitation to the Japanese EtherCAT Plug Fest 2013, which was held at the Japanese subsidiary headquarters of Beckhoff in Yokohama. The two-day event attracted 32 participants from 14 companies who were able to test the 5 master and 18 slave devices they brought along for interoperability evaluation using the ETG's Conformance Test Tool. The above-mentioned device profiles of the ETG's SEMI TWG also played an important role at this event: Although these profiles were only introduced in July of this year, semiconductor devices based on these profiles have already been successfully tested in Japan.